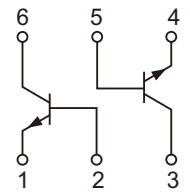
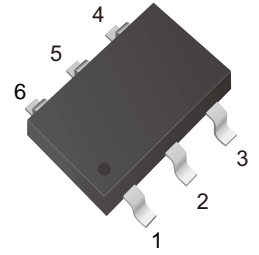


Dual Transistor (NPN+NPN)

Features

- Power Dissipation of 200mW
- Epitaxial Planar Die Construction
- Ideal for Low Power Amplification and Switching
- Lead free in comply with EU RoHS 2011/65/EU directives



Ordering Information

Part Number	Marking	Shipping	Reel
LT36T3904-TR3	K6N	3000PCS Tape&Reel	7 inches
LT36T3904-TR10	K6N	10000PCS Tape&Reel	13 inches

Maximum Ratings (Ta=25 unless otherwise noted)

Symbol	Parameter	Value	Units
V _{CB0}	Collector-Base Voltage	60	V
V _{CEO}	Collector-Emitter Voltage	40	V
V _{EBO}	Emitter-Base Voltage	6	V
I _C	Collector Current -Continuous	0.2	A
P _C	Collector Power Dissipation	0.2	W
T _J , T _{stg}	Operation Junction and Storage Temperature Range	-55~+150	°C

Electrical Characteristics (Ta=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Max	Unit
Collector-base breakdown voltage	V _{(BR)CBO}	I _C = 10μA, I _E =0	60		V
Collector-emitter breakdown voltage	V _{(BR)CEO}	I _C = 1mA, I _B =0	40		V
Emitter-base breakdown voltage	V _{(BR)EBO}	I _E = 10μA, I _C =0	6		V
Collector cut-off current	I _{CB0}	V _{CB} = 30 V, I _E =0		0.05	μA
Collector cut-off current	I _{CEX}	V _{CE} = 30 V, V _{BE(off)} =3V		0.05	μA
Emitter cut-off current	I _{EBO}	V _{EB} = 5 V, I _C =0		0.05	μA
DC current gain	h _{FE(1)}	V _{CE} = 1V, I _C = 0.1mA	40		
	h _{FE(2)}	V _{CE} = 1V, I _C = 1mA	70		
	h _{FE(3)}	V _{CE} = 1V, I _C = 10mA	100	300	
	h _{FE(4)}	V _{CE} = 1V, I _C = 50mA	60		
	h _{FE(5)}	V _{CE} = 1V, I _C = 100mA	30		
Collector-emitter saturation voltage	V _{CE(sat)1}	I _C = 10 mA, I _B = 1mA		0.2	V
	V _{CE(sat)2}	I _C = 50 mA, I _B = 5mA		0.3	V
Base-emitter saturation voltage	V _{BE(sat)1}	I _C = 10 mA, I _B = 1mA	0.65	0.85	V
	V _{BE(sat)2}	I _C = 50 mA, I _B = 5mA		0.95	V
Transition frequency	f _T	V _{CE} = 20V, I _C = 10mA, f = 100MHz	300		MHz
Delay time	t _d	V _{CC} = 3V, V _{BE} = 0.5V		35	nS
Rise time	t _r	I _C = 10mA, I _{B1} = -I _{B2} = 1mA		35	nS
Storage time	t _s	V _{CC} = 3V, I _C = 10mA		200	nS
Fall time	t _f	I _{B1} = -I _{B2} = 1mA		50	nS



Characteristics Curves

Fig.1 Static Characteristic

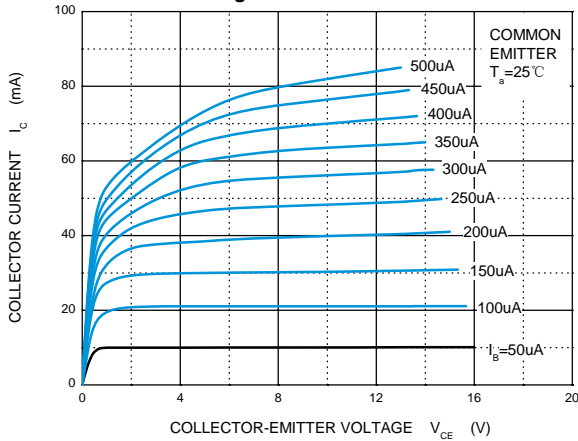


Fig.2 h_{FE} vs I_C

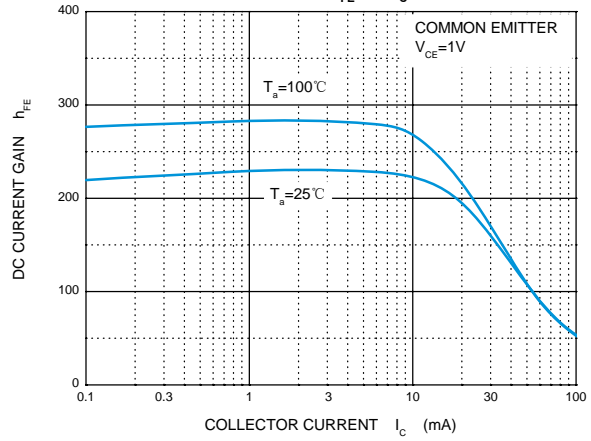


Fig.3 V_{CEsat} vs I_C

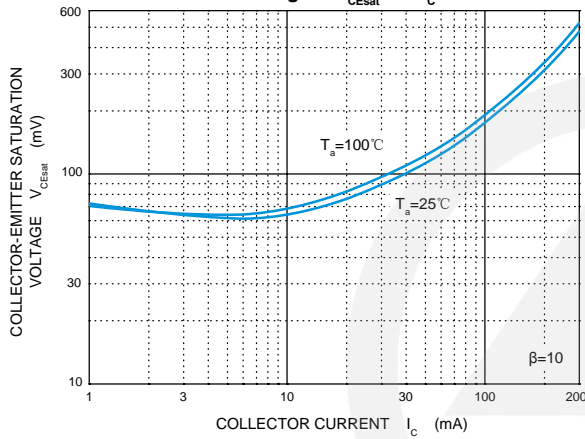


Fig.4 V_{BEsat} vs I_C

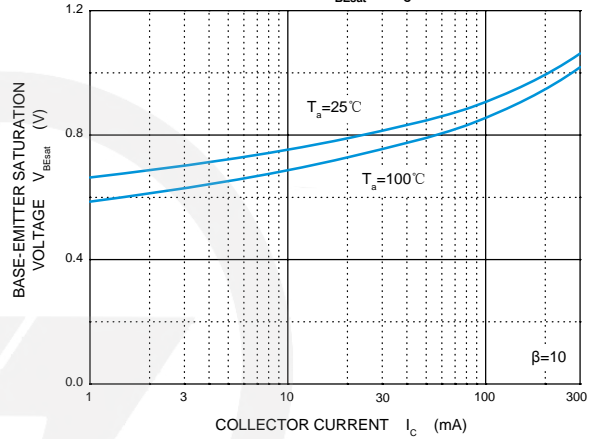


Fig.5 I_C vs V_{BE}

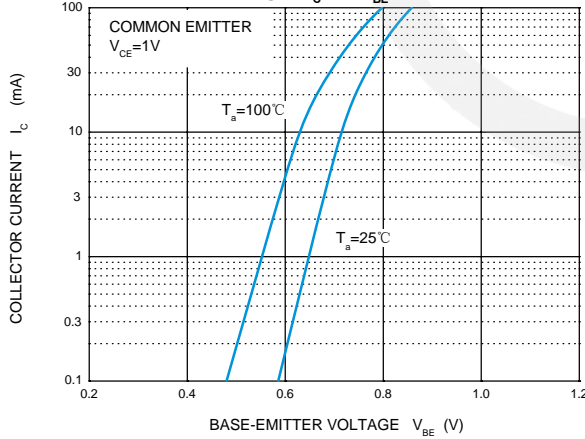


Fig.6 C_{ob}/C_{ib} vs V_{CB}/V_{EB}

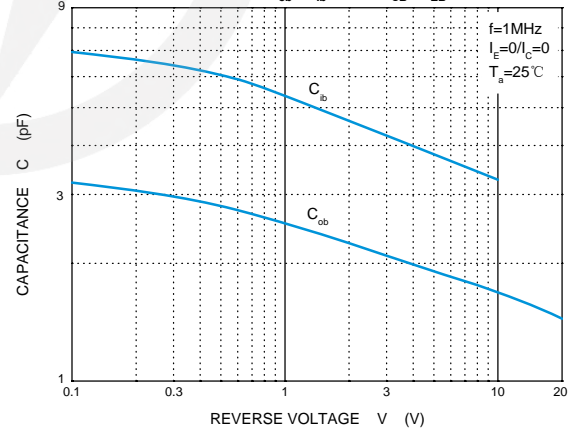


Fig.7 f_t vs I_C

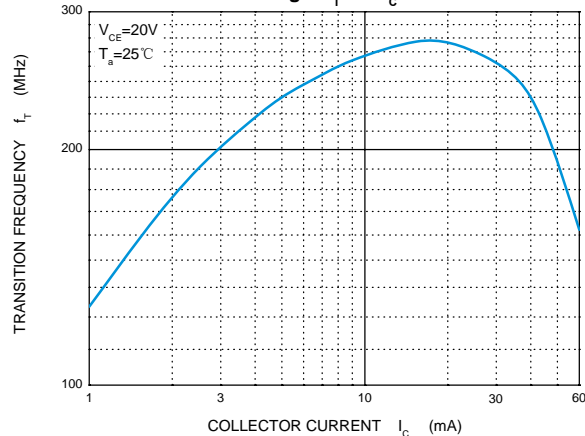
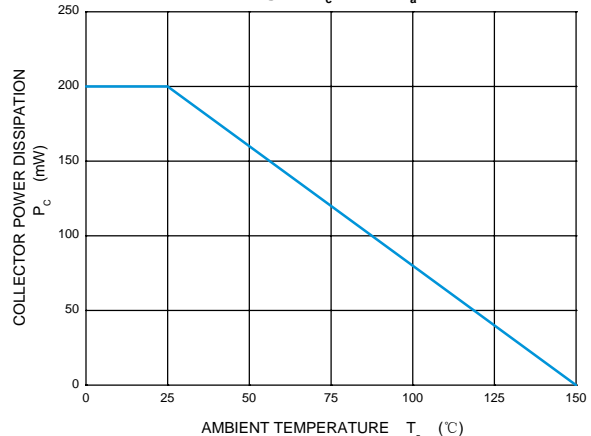
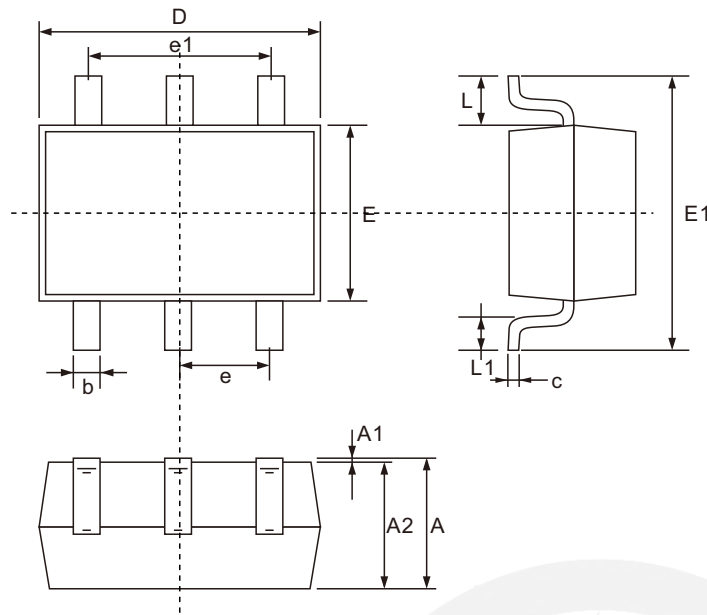


Fig.8 P_c vs T_a





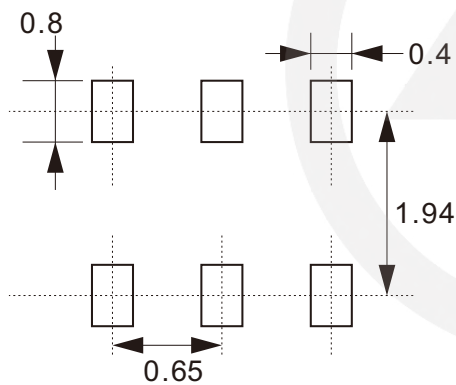
SOT-363 Package Outline



Unit: mm

SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	0.900	1.100
A1	0.000	0.100
A2	0.900	1.000
b	0.150	0.350
c	0.080	0.150
D	2.000	2.200
E	1.150	1.350
E1	2.150	2.450
e	0.650 TYP.	
e1	1.200	1.400
L	0.525 TYP.	
L1	0.260	0.460
θ	0°	8°

SOT-363 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$
3. The pad layout is for reference purpose only.

Carrier Tape Dimensions

Unit : mm

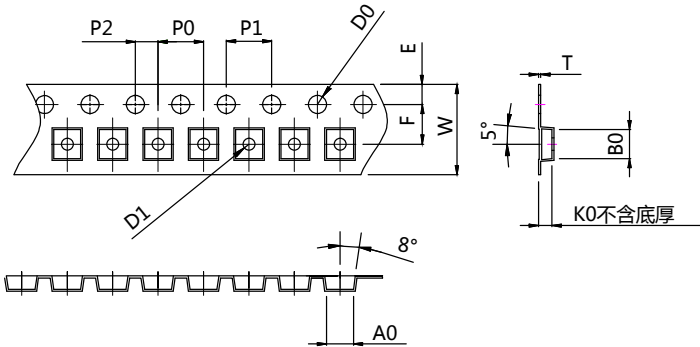


Diagram showing carrier tape dimensions: P2, P0, P1, D0, E, W, F, W, T, B0, D1, 8°, A0, K0不含底厚.

Symbol	Spec	Symbol	Spec
A0	2.36±0.10	P1	4.00±0.10
B0	2.55±0.10	W	8.00±0.10
K0	1.20±0.10	E	1.75±0.10
D0	1.55±0.10	F	3.50±0.05
D1	1.10±0.10	P2	2.00±0.10
P0	4.00±0.10	T	2.00±0.10

Reel Dimensions

Unit : mm

7" Reel

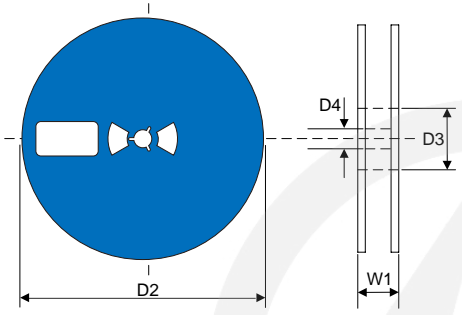


Diagram showing 7" Reel dimensions: D2, D3, D4, W1.

D2	Φ178.0±2.0
D3	Φ50
D4	13.0±0.5
W1	12±0.5

Quantity: 3000PCS

Reel Dimensions

Unit : mm

13" Reel

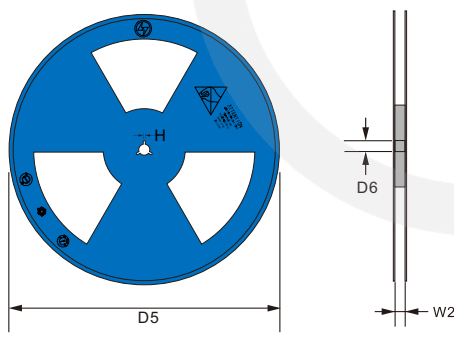
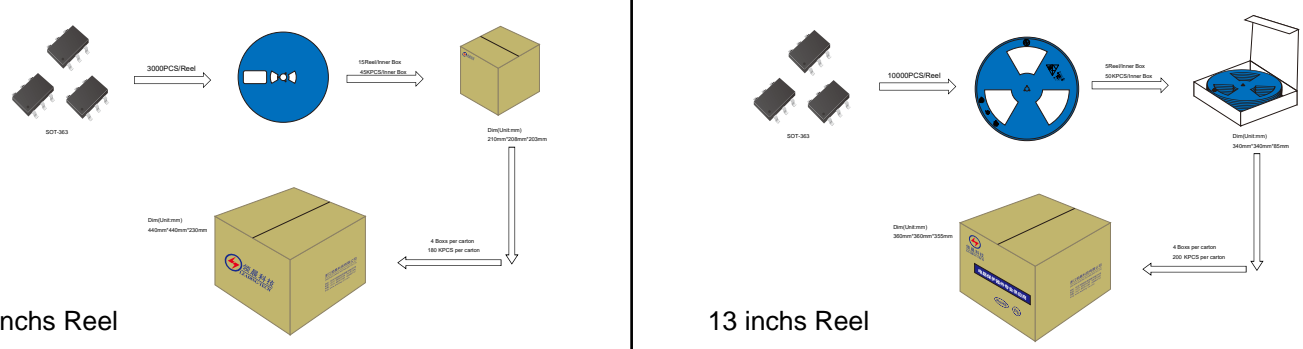


Diagram showing 13" Reel dimensions: D5, D6, H, W2.

D5	Φ330.0±2.0
D6	Φ13.5±0.5
H	2.5±1.0
W2	12±0.5

Quantity: 10000PCS

Packaging



Flow diagram showing packaging process for 7 inch and 13 inch reels.

7 inchs Reel

- 3000PCS/Reel
- 15 Reel/Inner Box (480PCS/Inner Box)
- Dim(LxHxW) 210mm*230mm*220mm
- 4 Boxes per carton, 1680PCS per carton
- Dim(LxHxW) 440mm*440mm*220mm

13 inchs Reel

- 10000PCS/Reel
- 5 Reel/Inner Box (5000PCS/Inner Box)
- Dim(LxHxW) 340mm*340mm*150mm
- 4 Boxes per carton, 20000PCS per carton
- Dim(LxHxW) 300mm*300mm*220mm



Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T _L to T _P)	3°C/second max.
Preheat	
-Temperature Min (T _{S min})	150°C
-Temperature Max (T _{S max})	200°C
-Time (min to max) (t _s)	60-180 seconds
T _{S max} to T _L	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature (T _L)	217°C
-Time (t _L)	60-150 seconds
Peak Temperature (T _P)	260°C
Time within 5°C of actual Peak Temperature (t _p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

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Version Update Information

Series NO.	Enactment/Revision Date	Effective Date	Version	Revision content	Revision Reason	Revision Person	Note
01	2024.05.27	2024.05.27	3.0	New File	/	Ding	